



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20250925000.2**  
**Qualification of TI Philippines as an additional Assembly/Test site**  
**for select devices**  
**Change Notification / Sample Request**

**Date:** September 25, 2025  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20250925000.2**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS22918TDBVRQ1	TPS22918TDBVRQ1
TPS22918TDBVTQ1	TPS22918TDBVTQ1
UCC28700QDBVRQ1	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20250925000.2		<b>PCN Date:</b>	September 25, 2025
<b>Title:</b>	Qualification of TI Philippines as an additional Assembly/Test site for select devices			
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	March 24, 2026	<b>Sample requests accepted until:</b>	November 24, 2025*	
*Sample requests received after November 24, 2025 will not be supported.				
<b>Change Type:</b>				
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>
<b>PCN Details</b>				
<b>Description of Change:</b>				
Texas Instruments is pleased to announce the qualification of TI Philippines as an additional Assembly/Test site for select devices. Assembly differences are as follows:				
<b>Group 1</b>				
	<b>Current A/T site</b>	<b>Additional A/T site</b>		
Assembly site	TFME	PHI		
Mount compound	SID# A-03	8095733		
Mold Compound	SID#R-17	4222198		
<b>Group 2</b>				
	<b>Current A/T site</b>	<b>Additional A/T site</b>		
Assembly site	TFME	PHI		
Mount compound	SID# A-09	4226215		
Mold Compound	SID#R-13	4222198		
Wire diam/type	1.0mil Au	1.0mil Cu		
Final wafer thickness	7.5mils	6.0mils		
Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.				
<b>Reason for Change:</b>				
Continuity of Supply				
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>				
None				
<b>Impact on Environmental Ratings</b>				
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.				
<input checked="" type="checkbox"/>	<b>RoHS</b>	<input checked="" type="checkbox"/>	<b>REACH</b>	<input checked="" type="checkbox"/>
<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>
<input checked="" type="checkbox"/>	<b>Green Status</b>	<input checked="" type="checkbox"/>	<b>IEC 62474</b>	<input checked="" type="checkbox"/>
<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>	No Change	<input checked="" type="checkbox"/>
<b>Changes to product identification resulting from this PCN:</b>				
<b>Assembly Site Information:</b>				
Assembly Site	Assembly Site Origin	Assembly Country	Assembly City	

	(22L)	Code (23L)	
TFME	NFM	CHN	Chongchuan
<b>TI Philippines</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio city</b>

**Sample Product Shipping Label (not actual product label)**



MADE IN: Malaysia  
2DC: 2Q:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM: 39  
**LBL: 5A (L)T0:1750**





(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

<b>Group 1 Product Affected:</b>	
TPS22918TDBVRQ1	TPS22918TDBVTQ1
<b>Group 2 Product Affected:</b>	
UCC28700QDBVRQ1	

**Group 1 Qualification Report**  
**Automotive Qualification Summary**  
(As per AEC-Q100 Rev. J and JEDEC Guidelines)  
Approve Date 25-March-2025

**Product Attributes**

Attributes	Qual Device: <u>TPS22918TDBVRQ1</u>	Qual Device: <u>TPS22918TDBVTQ1</u>	QBS Package Reference: <u>UCC27517AQDBVRQ1</u>	QBS Package, Process Reference: <u>TPS22810TDBVRQ1</u>
Automotive Grade Level	Grade 2	Grade 2	Grade 1	Grade 2
Operating Temp Range (C)	-40 to 105	-40 to 105	-40 to 125	-40 to 105
Product Function	Power Management	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB
Assembly Site	PHI	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT
Package Designator	DBV	DBV	DBV	DBV
Pin Count	6	6	5	6

QBS: Qual By Similarity, also known as Generic Data  
Qual Device TPS22918TDBVRQ1 is qualified at MSL2 260C  
Qual Device TPS22918TDBVTQ1 is qualified at MSL2 260C

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration		Qual Device:	Qual Device:	QBS Package Reference:	QBS Package, Process Reference:
									TPS22918TDBVRQ1	TPS22918TDBVTQ1	UCC27517AQDBVRQ1	TPS22810TDBVRQ1
<b>Test Group A - Accelerated Environment Stress Tests</b>												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	-	-	3/612/0	-
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	3/15/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/135/0
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>												
<b>Test Group C - Package Assembly Integrity Tests</b>												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	1/15/0	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/15/0	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-	-	3/30/0	3/30/0
<b>Test Group D - Die Fabrication Reliability Tests</b>												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements				
Tddb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements				
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements				
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements				
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements				
<b>Test Group E - Electrical Verification Tests</b>												
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

### Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-063

## Group 2 Qualification Report Automotive Qualification Summary (As per AEC-Q100 Rev. J and JEDEC Guidelines)

Approve Date 25-March-2025

### Product Attributes

Attributes	Qual Device:	QBS Package Reference:	QBS Package Reference:	QBS Process Reference:
	<u>UCC28700QDBVRQ1</u>	<u>TLV2401QDBVRQ1</u>	<u>SN6505AQDBVRQ1</u>	<u>UCC28730QDRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Signal Chain	Interface	Power Management
Wafer Fab Supplier	MH8	DL-LIN	RFAB	MH8, MH8
Assembly Site	PHI	PHI	PHI	MLA
Package Group	SOT	SOT	SOT	SOIC
Package Designator	DBV	DBV	DBV	D
Pin Count	6	5	6	7

QBS: Qual By Similarity, also known as Generic Data

Qual Device UCC28700QDBVRQ1 is qualified at MSL1 260C

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	QBS Package Reference:	QBS Package Reference:	QBS Process Reference:
								<u>UCC28700QDBVRQ1</u>	<u>TLV2401QDBVRQ1</u>	<u>SN6505AQDBVRQ1</u>	<u>UCC28730QDRQ1</u>
<b>Test Group A - Accelerated Environment Stress Tests</b>											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	3/0/0	1/0/0	-
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	-	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	1/77/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	3/231/0	1/77/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	1/77/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	1/5/0	3/15/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	-	-	-	3/36/0

HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	1/45/0	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	3/231/0
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	3/231/0	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/1 <sup>1</sup>
<b>Test Group C - Package Assembly Integrity Tests</b>											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/15/0	1/30/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/15/0	1/30/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	1/10/0	3/30/0
<b>Test Group D - Die Fabrication Reliability Tests</b>											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements			
TDD	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements			
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements			
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements			
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements			
<b>Test Group E - Electrical Verification Tests</b>											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	750 Volts	-	1/3/0	1/3/0	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	1/30/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2411-036

[1]-One unit failed post 48 hrs ELFR. Failure analysis indicated that this unit most likely failed due to mishandling related EOS. Contact TI Quality group for full 8D report.

## Automotive Q006 Qualification Summary

### AEC-Q006 Table 3a: Integrated Circuit Qualification Test Requirements

Qualification Device(s) **BiCMOS analog**

Technology attributes covered by this Q006 qualification

- **Silicon attributes:** 300mm LBCx processes finished with BOAC in TI CLARK.
- **Bond pad metal technology:** 'Copper top'
- **Package family :** SOT23 packages in TIPI
- **Wire type :** 1.3 Mil Copper wire / 0.96 Mil copper / 0.8 Mil copper wire.

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

					SOT23 Package	DBV (5 pin)	DBV (5 pin)	DDF (8 pin)	
					Wire	1.3 mil Cu	0.96 mil Cu	0.8 Mil Cu	
Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: TPS22810DBV	Qual Device: UCC2751xDBV	Qual Device: LM74700QDDFQ1
<b>Test Group A - Accelerated Environment Stress Test</b>									
					SAM Analysis, Pre Stress	-	Passed	Passed	Passed
PC	A1	JESD22-113	-	-	<b>Preconditioning</b>	<b>Level 3-260C</b>	<b>Passed</b>	<b>Passed</b>	<b>Passed</b>
			-	-	SAM Analysis, Post-Precon on 11 marked (or 22 random) units per lot before THB, TC, PTC and HTSL		Passed : No delamination	Passed : No delamination	Passed : No delamination
HAST	A2	JESD22-A101	3	77	<b>BHAST, Vmax/130C/85% RH</b>	<b>96 Hours</b>	<b>3/231/0</b>		<b>3/231/0</b>
			3	1	Cross Section, Post bHAST 96 Hours	-	3/3/0		3/3/0
			3	11 / 22	SAM Analysis, Post bHAST, 96 Hours	-	3/33/0		Skipped to 2x
			3	3	Wire Bond Shear, Post bHAST, 96 Hours	units	3/9/0		3/9/0
			3	3	Bond Pull over Stitch, post bHAST, 96 Hours	units	3/9/0		3/9/0
			3	3	Bond Pull over Ball, Post bHAST, 96 Hours	units	3/90/0		3/90/0
HAST	A2	JESD22-A101	3	70	<b>BHAST, Vmax/130C/85% RH</b>	<b>192 Hours</b>	<b>3/210/0</b>		<b>3/210/0</b>
			3	1	Cross Section, Post bHAST 192 Hours	-	3/3/0		3/3/0
			3	11 / 22	SAM Analysis, Post bHAST, 192 Hours	-	3/33/0		3/66/0
			3	2	Wire Bond Shear, Post bHAST, 192 Hours	units	3/9/0		3/9/0
			3	2	Bond Pull over Stitch, post bHAST, 192 Hours	units	3/9/0		3/9/0
			3	2	Bond Pull over Ball, Post bHAST, 192 Hours	units	3/9/0		3/9/0
TC	A4	JESD22-A104	3	77	<b>Temperature Cycle, -65/150C</b>	<b>500 Cycles</b>	<b>3/231/0</b>	<b>1/77/0</b>	<b>3/231/0</b>
			3	1	Cross Section, Post T/C 500 Cycles	-	3/3/0	1/1/0	3/3/0
			3	11 / 22	SAM Analysis, Post T/C, 500 Cycles	-	3/33/0	1/11/0	3/66/0
			3	3	Wire Bond Shear, Post T/C 500 Cycles	units	3/9/0	1/3/0	3/9/0
			3	3	Bond Pull over Stitch Post T/C 500 Cycles	units	3/9/0	1/3/0	3/9/0
			3	3	Bond Pull over Ball Post T/C 500 Cycles	units	3/9/0	1/3/0	3/9/0
TC	A4	JESD22-A104	3	70	<b>Temperature Cycle, -65/150C</b>	<b>1000 Cycles</b>	<b>3/210/0</b>	<b>1/70/0</b>	<b>3/210/0</b>
			3	1	Cross Section, Post T/C 1000 Cycles	-	3/3/0	1/1/0	3/3/0
			3	11 / 22	SAM Analysis, Post T/C, 1000 Cycles	-	3/33/0	1/11/0	3/66/0
			3	2	Wire Bond Shear, Post T/C 1000 Cycles	units	3/6/0	1/2/0	3/6/0
			3	2	Bond Pull over Stitch, Post T/C, 1000 Cycles	units	3/6/0	1/2/0	3/6/0
			3	2	Bond Pull over Ball, Post T/C, 1000 Cycles	units	3/6/0	1/2/0	3/6/0
PTC	A5	JESD22-A105	1	45	<b>Power Temperature Cycle</b>	<b>1000 Cycles</b>	<b>NA</b>	<b>NA</b>	<b>NA</b>

PTC	A5	JESD22-A105	1	45	Power Temperature Cycle	2000 Cycles	NA	NA	NA
HTSL	A6	JESD22-A103	3	45	High Temp Storage Bake 150C*	1000 Hours	3/135/0		3/135/0
			3	1	Cross Section, Post HTSL 1000 Hours	-	3/3/0		3/3/0
			3	44	High Temp Storage Bake 150C	2000 Hours	-		3/132/0
			3	1	Cross Section, Post HTSL 2000 Hours	-	-		3/3/0
			3	45	High Temp Storage Bake 175C	500 hours		1/45/0	
			3	1	Cross Section, Post HTSL 500 Hours			1/1/0	
			3	44	High Temp Storage Bake 175C	1000 hours		1/44/0	
			3	1	Cross Section, Post HTSL 1000 Hours			1/1/0	
<p>*Device was released as Q100 grade 2 where 1000 hours x 150C is 2x duration.</p> <p><b>Summary post-reliability construction analysis.</b></p> <p>1. CSAM shows no delamination after BHAST and Temperature cycling</p> <p>2. Cross sections showed no evidence of cracking or oxidation within the bonds.</p> <p>3. Bond pulls, shears and stitch pulls show no degradation – distribution showing similar performance to unaged devices</p>									

TI Qualification ID: 20170418-121595 , 20191011-131872 and 20200416-133706

ZVEI ID: SEM-PA-07, SEM-PA-08, SEM-PA-11, SEM-PA-18, SEM-PW-03, SEM-TF-01

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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